

**IN THE CLAIMS**

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2. (Amended) The structure as recited in claim 1, wherein the metal layer includes copper.

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4. (Amended) The structure as recited in claim 1, further comprising a barrier layer disposed between the interconnect and the metal layer to prevent diffusion therebetween.

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11. (Amended) The structure as recited in claim 10, wherein the metal layer includes copper.

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